

Resource Summary Report

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Texas State University Wafer Bonder system

RRID:SCR_028207

Type: Tool

Proper Citation

Texas State University Wafer Bonder system (RRID:SCR_028207)

Resource Information

URL: <https://sro.txst.edu/sro-facilities/sro-nrsc/sro-nrsc-wb.html>

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Description: Facility EVG 501 wafer bonder system applies pressure up to 10kN and temperature up to 450C to samples with prepared surfaces (specific chemical surface termination). When the system mechanically brings these surfaces into contact the temperature and pressure sequence activates chemical bonds at the interfaces that fuse the sample surfaces together. A precision wafer bonding system used to join semiconductor wafers using thermal, adhesive, or anodic bonding techniques for device integration.

Synonyms: Wafer Bonder (EVG520)

Resource Type: instrument resource

Keywords: wafer bonding, MEMS, semiconductor integration, microfabrication

Availability: Restricted

Resource Name: Texas State University Wafer Bonder system

Resource ID: SCR_028207

Alternate URLs: <https://sro.txst.edu/sro-facilities/sro-nrsc.html>

Record Creation Time: 20260327T054534+0000

Record Last Update: 20260801T191439+0000

Ratings and Alerts

No rating or validation information has been found for Texas State University Wafer Bonder system.

No alerts have been found for Texas State University Wafer Bonder system.

Data and Source Information

Source: [SciCrunch Registry](#)

Usage and Citation Metrics

We have not found any literature mentions for this resource.